

#### **General Information**

In many industrial sectors and fields of research, temperature measurement is one of the most important parameters which determines product quality, security, and reliability. Temperature sensors are available in several types all of which have a unique performance characteristic. The performance capability of the various sensors are a result of the manufacturing process and component materials associated with their technologies and intended application. It is IST Charter to produce sensors that exceed the industry standard of temperature measurement with additional capability to directly replace older traditional methods and provide the maximum performance. To this end IST has concentrated its development and manufacturing on the process and materials of high-end thin-film temperature sensors. Additionally these processes, partially derived from the semiconductor industry allows IST to manufacture sensors in very small dimensions. Because of their low thermic mass thin-film sensors that combine the good features of traditional wire wound platinum sensors such as accuracy, long-term stability, repeatability, interchangeability and wide temperature range, with the advantages of mass-production, which contributes to their optimal price/performance ratio.

#### **Sensor Construction**

The temperature sensor consists of a photo-lithographically structured, high-purity platinum coating arranged in the shape of a meander. The platinum thin-film structures are laser trimmed to form resistive paths with very precisely defined basic value of the resistivity. The sensors are covered with a glass passivation layer; to protect the sensor against mechanical and chemical damage. The bonded leadwires which are additionally covered with a drop of glass make electrical contacts to the resistive structure.

## **Typical Features**

- brief response time
- small dimensions
- excellent long-term stability
- resistant against vibration and temperature shocks
- low self-heating rate
- simple interchangeability
- excellent price/performance ratio

## **Response Time**

The response time  $T_{0.63}$  is the time in seconds the sensors need to respond to 63% of the change in temperature. The response time depends on the sensor dimensions, the termal contact resistance and the encloser medium.

### Long-Term Stability

The change of ohmage after 1,000 hrs at maximum operating temperature until the 7W types amounts to less than 0.03%.

## **Self Heating**

To measure the resistance an electric current has to flow through the element, which will generate heat energy resulting in errors of measurement. To minimize the error, the testing current should be kept low (approximately 1 mA for pt-100). Temperature error  $\Delta T = RI^2 / E$ ; with E = self-heating coefficient in mW/K R = resistance in k $\Omega$ , I = measuring current in mA

## **Measurement current**

The amount of thermal transfer from the sensor in application determines how much measuring current can be applied. There is no bottom limit of the measurement current with platinum thin-film. The measurement current depend highly on the application in use. For sensors from 750°C - 1000°C (7W, 8W, 10W) the measurement current must limited at max. 1 mA.

## We recommend at:

100 Ω:	typ. 1 mA	max. 5 mA
500 Ω:	typ. 0.5 mA	max. 3 mA
1000 Ω:	typ. 0.3 mA	max. 2 mA
2000 Ω:	typ. 0.2 mA	max. 1 mA
10000 Ω:	typ. 0.1 mA	max. 0.3 mA





## HUMIDITY

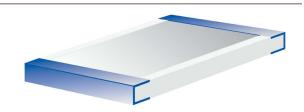
# SMD 0805 + 1206 Platinum and Nickel Thin-Film Chip Sensor

## **Product**

To meet the market requirements for increasingly more efficient and economical manufacturing processes, we have developed the SMD 1206 series. A platinum or nickel temperature sensor which is designed for use in markets with a high degree of automation in their production line. This thin-film sensor combines the excellent characteristics of platinum or nickel sensors such as accuracy, long-term stability and reproducibility with the advantages of large-scale production and an optimal price/performance ratio.

## **Advantages**

- · Optimised for pick-and-place machines
- · Cost-effective assembling
- Easy handling
- · Platinum or Nickel thin film elements
- Lead-free (acc. RoHS)



#### **Technical Data**

Nominal resistance:  $100\Omega$ ,  $500\Omega$  or  $1000\Omega$ 

Temperature range:  $-50 \,^{\circ}\text{C}$  to  $+150 \,^{\circ}\text{C}$  (1P, 2P);  $-50 \,^{\circ}\text{C}$  to  $+250 \,^{\circ}\text{C}$  (3P, 4P) Temperature coefficient: Pt: TCR = 3850ppm/K; Ni: TCR = 6180ppm/K

Dependence of Resistivity: DIN 60751 (Platinum); former DIN 43760 (Nickel 6180ppm/K)

other resistivities on request

Classes: Pt: DIN class A; DIN class B; 2x DIN class B

Ni: DIN, 1/2 DIN (IST cl. A)

DIN 43760: ± 400mK (0°C); ± 7mK/K (>0°C); ± 28mK/K (<0°C)

Soldering connection: Contacts:

1P = Contacts tin coated (62Sn/36Pb/2Ag), LMP lead contained

2P = Contacts tin coated (96.5Sn/3Ag/0.5Cu), LMP lead free, RoHS conform

3P = Contacts tin coated (5Sn/93.5Pb/1.5Ag), HMP, RoHS conform

4P\* = Contacts gold plated, solderable film

\*there is no ensurance for DIN class A, due to the changed resistance value

after soldering.

\*bondable contacts without bumps available on request.

Solderability:  $235 \,^{\circ}\text{C} \le 8s \text{ (DIN IEC } 68 \text{ 2-20, Ta Meth } 1)$ Resistance to soldering heat:  $260 \,^{\circ}\text{C} \ 10x \text{ (DIN IEC } 68 \text{ 2-20, Ta Meth. } 1A)$ Long-term stability: Pt: max. Drift = 0.04% after 1000h at 130  $\,^{\circ}\text{C}$ Ni: max. Drift = 0.1% after 1000 h at 130  $\,^{\circ}\text{C}$ 

Ni. max. Dilit = 0.1% after 1000 if at 130 G

Response time: Water (0.4m/s):  $T_{0.63} = 0.25s$  (1206)  $T_{0.63} = 0.2s$  (0805)

Air (1m/s):  $T_{0.63} = 5.0s$  (1206)  $T_{0.63} = 4.0s$  (0805)

The response time refers to the chip, unspoilt

Measuring current:  $0.5\text{mA} (100\Omega)$ ;  $0.4\text{mA} (500\Omega)$ ;  $0.3\text{mA} (1000\Omega)$ Self heating: Water [mW/°C]: 40 (1206, 0805)

Air [mW/°C]: 4 (1206, 0805)

Dimensions: Pt: 0805 (2.0 x 1.2mm); 1206 (3.2 x 1.6mm)

Ni: 1206 (3.2 x 1.6mm)

Other Nominal resistances and tolerances on request.





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#### **Nominal values**

The nominal or rated value of the sensor is the target value of the sensor resistance at  $0^{\circ}$  C. The temperature coefficient  $\alpha$  is defined

as  $\alpha = \frac{R_{100} - R_0}{100 \cdot R_0}$  [K<sup>-1</sup>] and has the numerical value of 0.00385 K<sup>-1</sup> according to DIN IEC 751.

In practice, a value multiplied by  $10^6$  is often entered: TCR =  $10^6 * \frac{R_{100} - R_0}{100 \cdot R_0}$  [ppm/K]. In this case, the numerical value is 3850 ppm/K.

## **Temperatur Characteristic Curve**

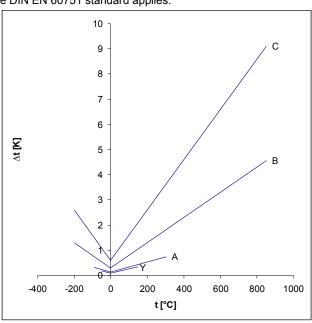
The characteristic temperature curve determines the dependence of the electrical resistivity on the temperature. The following definition of the temperature curve according to the DIN EN 60751 standard applies:

-200 bis 0°C 
$$R(t) = R_0 (1 + A * t + B * t^2 + C * [t-100] * t^3)$$
0 bis 850°C 
$$R(t) = R_0 (1 + A * t + B * t^2)$$
Platinum (3850 ppm/K):
$$A = 3.9083 * 10^{-3} [°C^{-1}]; B = -5.775 * 10^{-7} [°C^{-2}];$$

$$C = -4.183 * 10^{-12} [°C^{-4}]$$
Platinum (3750 ppm/K):
$$A = 3.8102 * 10^{-3} [°C^{-1}]; B = -6.01888 * 10^{-7} [°C^{-2}];$$

$$C = -6 * 10^{-12} [°C^{-4}]$$
Platinum (3770 ppm/K):
$$A = 3.92 * 10^{-3} [°C^{-1}]; B = -6.03 * 10^{-7} [°C^{-2}];$$

R<sub>0</sub> = Resistance value in ohm at 0°C; t = temperature in accordance with ITS 90



Tolerance field

## **Tolerance Classes**

temperature sensors are divided into classes according to their limit deviations:

Class	+/- limit deviations in °C (K)	IST AG designation	area of validity of temperature class
DIN 60751, class B	0.30 + 0.005 x   t	В	-200°C bis 850°C
DIN 60751, class A	0.15 + 0.002 x   t	Α	-90°C bis 300°C
1/3 DIN 60751, class B	0.10 + 0.0017 x   t	Υ	-50°C bis 150°C
2DIN 60751, class B	0.60 + 0.01 x   t	С	-200°C bis 850°C
1/5 DIN 60751, class	B 0.06 + 0.001 x   t	1/5	on request
1/10 DIN 60751, class	s B 0.03 + 0.0005 x   t	1/10	on request

| t | is the numerical value of the temperature in °C without taking into account either negative or positive signs. Special selection of sensors upon request (e.g. pairings, grouping, special tolerances)







## **Response Times and Self-Heating**

Dimension Number	Sensor Size	R	Respo	nse T	ime i	n secor	Self-Heating				
	LxWxT/Hinmm	Water 0.4 m/s			Air 1m/s			-	ater 0 m/s	Air v = 0 m/s	
		T <sub>0.5</sub>	T <sub>0.63</sub>	T <sub>0.9</sub>	T <sub>0.5</sub>	T <sub>0.63</sub>	T <sub>0.9</sub>	mW/K	∆T[mK]*	mW/K	ΔT[mK] <sup>*</sup>
MiniSens 161	1.6 x 1.2 x 0.25 / 0.9	0.05	0.08	0.18	1	1.2	2.5	12	8.3	1.8	56
SlimSens 308	3.0 x 0.8 x 0.25 / 0.6	0.08	0.10	0.25	1.2	1.5	3.5	15	6.7	2.2	46
232	2.3 x 2.0 x 0.25 / 0.9	0.09	0.12	0.33	2.7	3.6	7.5	40	2.5	4	25
202	2.0 x 2.0 x 0.63 / 1.3	0.12	0.18	0.42	4	5.4	11	36	2.8	3.6	28
216	2.0 x 1.6 x 0.63 / 1.3	0.11	0.16	0.38	3.6	4.9	10.2	32	3.1	3.2	31
232	2.3 x 2.0 x 0.63 / 1.3	0.15	0.2	0.55	4.5	6	12	40	2.5	4	25
325	3.0 x 2.5 x 0.63 / 1.3	0.25	0.3	0.7	5.5	7.5	16	90	1.1	8	13
516	5.0 x 1.6 x 0.63 / 1.3	0.25	0.3	0.7	5.5	7.5	16	80	1.3	7	14
520	5.0 x 2.0 x 0.63 / 1.3	0.25	0.3	0.75	6	8.5	18	80	1.3	7	14
525	5.0 x 2.5 x 0.63 / 1.3	0.33	0.4	0.85	6.5	9	19	90	1.1	8	13
538	5.0 x 3.8 x 0.63 / 1.3	0.35	0.4	0.9	7.5	10	20	140	0.7	10	10
505	5.0 x 5.0 x 0.63 / 1.3	0.4	0.5	1.1	8	11	21	150	0.7	11	9
102	10.0 x 2.0 x 0.63 / 1.3	0.33	0.4	0.85	7.5	10.5	20	140	0.7	10	10
281	1 x 13 x Ø 2.8	2.5	4.5	8	10	15	28	60	1.7	5.5	18
281	2 x 13 x Ø 2.8	2	2.5	5.5	10	12	22	45	2.2	4	25
451	1 x 13 x Ø 4.5	8	10	22	12	22	40	85	1.2	8	13
451	2 x 13 x Ø 4.5	5	6	14	16	18	37	60	1.7	6.5	15
SMD 1206	3.2 x 1.6 x 0.4	0.15	0.25	0.45	3.5	4.2	10	55	1.8	7	14
SMD 0805	2.0 x 1.2 x 0.4	0.10	0.12	0.33	2.5	3	8	38	2.6	4	25
FC 0603	1.5 x 0.75 x 0.4	0.08	0.10	0.25	1.8	2.2	5.5	25	4	2.5	40

<sup>\*</sup>self heating  $\Delta T[mK]$  measured for Pt100 at 1mA measurement current at 0°C

L: Chip length (sensor length without connections) W: Sensor width

T: Chip thickness (sensor thickness without connections)

H: Sensor height (incl. connections and strain relief)

Notification: The values in the table are of informative nature only. Due to different measurement conditions you might assess deviant self heating and response time values of your application.

## **Tolerances of dimensions**

Sensor width (W) ± 0.2 mm Sensor length (L) ± 0.2 mm Sensor height (H) ± 0.3 mm Sensor thickness (T) ± 0.1 mm Wire length ± 1.0 mm Tube length ± 0.2 mm Tube diameter ± 0.1 mm



1P - Product Series

Temperature Range: -60°C... +150°C

## Temperature sensors in SMD construction Soldering depot, RoHs conform (reflow soderable) \*only Flip Chip assembly

#### **Technical Data**

Temperature range: -50°C to +150°C (1P, 2P) ; -50°C to +250°C (3P, 4P)

Classes: Pt: DIN class A; DIN class B; 2x DIN class B

Soldering connection: Contacts:

1P = Contacts tin coated (62Sn/36Pb/2Ag), LMP lead contained

2P = Contacts tin coated (96.5Sn/3Ag/0.5Cu), LMP lead free, RoHS conform

3P = Contacts tin coated (5Sn/93.5Pb/1.5Ag), HMP, RoHS conform

4P = Contacts gold plated, solderable film

- there is no ensurance for DIN class A,

due to the changed resistance value after soldering.

- bondable contacts without bumps available on request.

Solderability:  $235^{\circ}\text{C} \le 8s \text{ (DIN IEC } 68 \text{ 2-20, Ta Meth } 1)$ Resistance to soldering heat:  $260^{\circ}\text{C} = 10x \text{ (DIN IEC } 68 \text{ 2-20, Ta Meth. } 1\text{A})$ Long-term stability: Pt: max. Drift = 0.04% after 1000h at 130°C

Dimensions in mm	Nominal Resistance at 0°C in Ohm	Chip-Dimensions in mm	Description
1,2 0,4	100	LxW 2.0 x 1.2	P0K1.0805.xP.x
	500	LxW 2.0 x 1.2	P0K5.0805.xP.x
	1000	LxW 2.0 x 1.2	P1K0.0805.xP.x
3,2	100	LxW 3.2 x 1.6	P0K1.1206.xP.x
1,6	500	LxW 3.2 x 1.6	P0K5.1206.xP.x
1,6	1000	LxW 3.2 x 1.6	P1K0.1206.xP.x
1,5	100	LxW 1.5 x 0.75	P0K1.0603.xFC.x*
	500	LxW 1.5 x 0.75	P0K5.0603.xFC.x*
	1000	LxW 1.5 x 0.75	P1K0.0603.xFC.x*



## **Platinum Temperature Sensors** TEMPERATURE Order Information





	1	K	0.	5	2	0.	4	W.	B.	0	1	0.	M		Example
													Spe	 ecials	
													Т		e thickness 0.25 mm
													D		e thickness 0.38 mm
													R		
														Sintered	
													M U	Inverted	ed backside
													S	Special*	welding
										Col	nne	ction		gth in mr	1
									Tol			class			
									Α	Cla	ss D	OIN A	١		
									В	Cla	ss D	DIN E	}		
									С			DIN			
									Υ	-		ss D	IN B		
									Р	Pai		<b>.</b>			AD = Contents tin as at all
									G K	Gro	ups	i" ner sj	aggif	fic*	1P = Contacts tin coated, LMP lead contained
								Fyto	nsio			101 3	Jecii	IC	2P = Contacts tin coated.
								S				n line	÷)		LMP lead free, RoHS
										olde			,		conform
								Р	Ove	rall (	(SMI	D)		$\rightarrow$	3P = Contacts tin coated,
								FC	Tin-				cts		HMP, RoHS conform
								W	Wire						4P = Contacts gold plated,
									Per			ar le	ads		solderable film
								FW	Flat	-					
												ntac	ts		
								E L	-	mele		/ires ande	.d	iroc	
								K				oecifi		1162	
							Ten	npera				JCCIII	C		
							1		°C to			;			
							2		°C to						
							3	-200	°C to	30	0°C	;			
							4	-200							
							6	-200							
							7		°C to						
							8 10		°C to						
				Med	hani	ical d							nene	sions) in m	m
	Res	istar	ice v			nm at			<b>3</b> (30	o va	i iou	3 uiii	10113		
Cha	aract				01	at									
			ppm/												
W					tend	ed te	mper	ature	rang	e in	clas	s A)			
U	Pt 3	750	ppm/	ΚÌ											
G			ppm/												
aterial			ation												
Plat				i£!	4! -		!		41		4 -				

\* Additional details, specifications required from the customer.

## Order example:

4 5 6 7 8

P 1K0. 520. 4 W. B. 010. M 1: Material identification

Resistance value in ohm Chip dimension

Temperature range Extension

Tolerance class Connection length

Special

= Platinum Temperature Sensor

=  $1'000 \Omega / 0^{\circ}C$ 

= 5 mm x 2 mm = + 400°C

= Wire connections (Ag, Ø 0.25 mm)

= DIN EN 60751 class B

= 10 mm

= metallised backside

Specifications are subject to change without notice





All mechanical dimensions are valid at 25°C ambient temperature, if not differently indicated. All data except the mechanical dimensions only have information purposes and are not to be understood as assured characteristics. Technical changes without previous announcement as well as mistakes reserve. The information on this data sheet was examined carefully and will be accepted as correct; No liability in case of mistakes. Load with extreme values during a longer period can affect the reliability